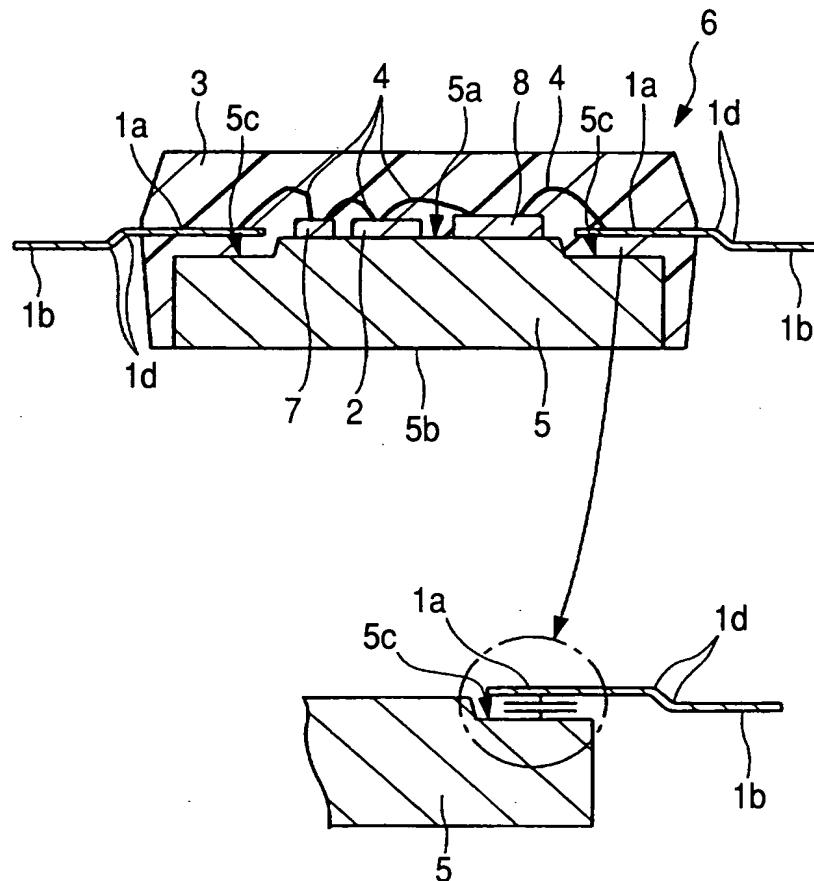


FIG. 2



1a: INNER LEAD
2: FET CHIP
4: WIRE (METAL WIRE)
5: HEAT SINK (METAL PLATE)
5c: DEPRESSED PORTION
7: MOS-C CHIP

FIG. 4

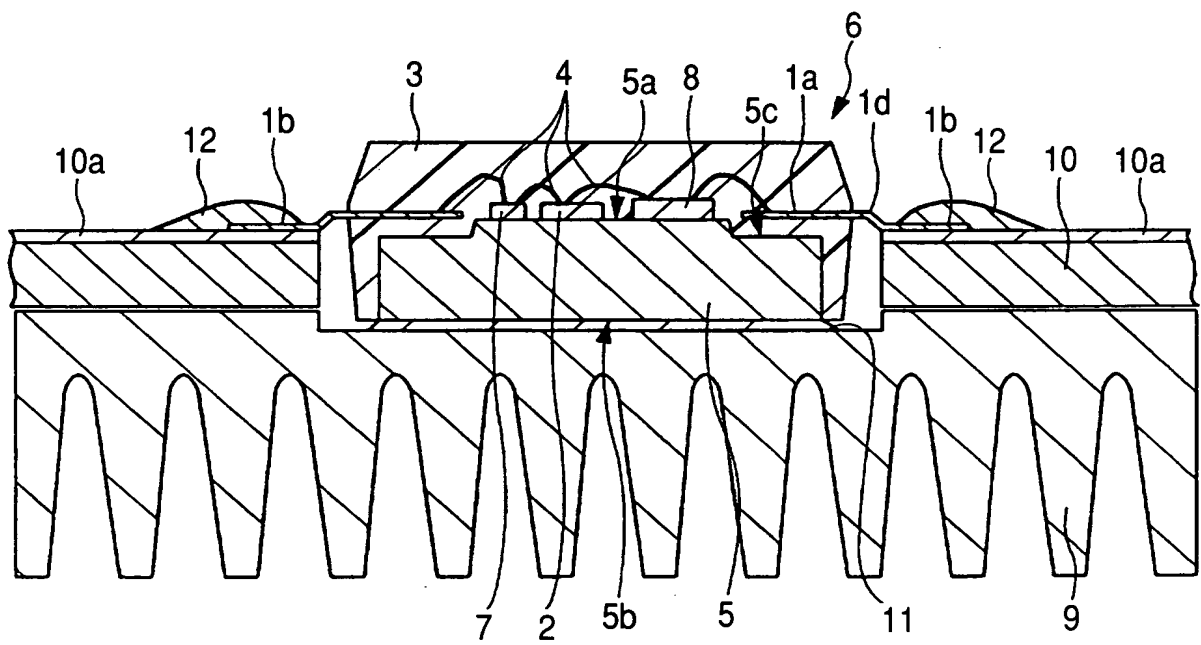


FIG. 5

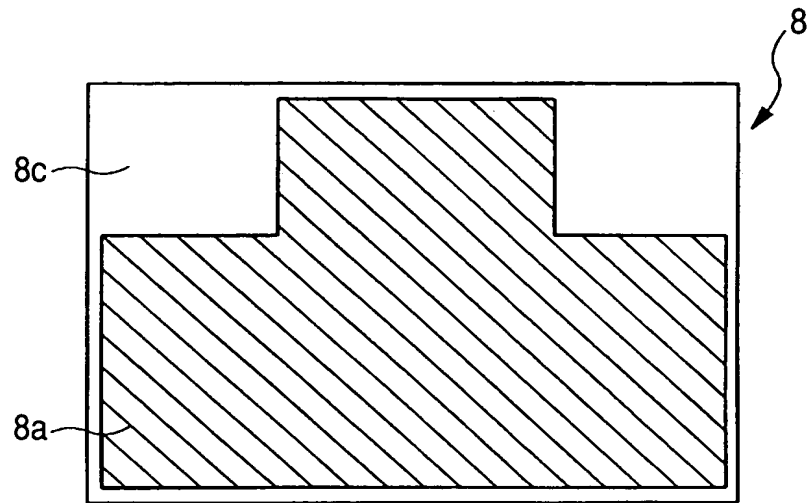


FIG. 6

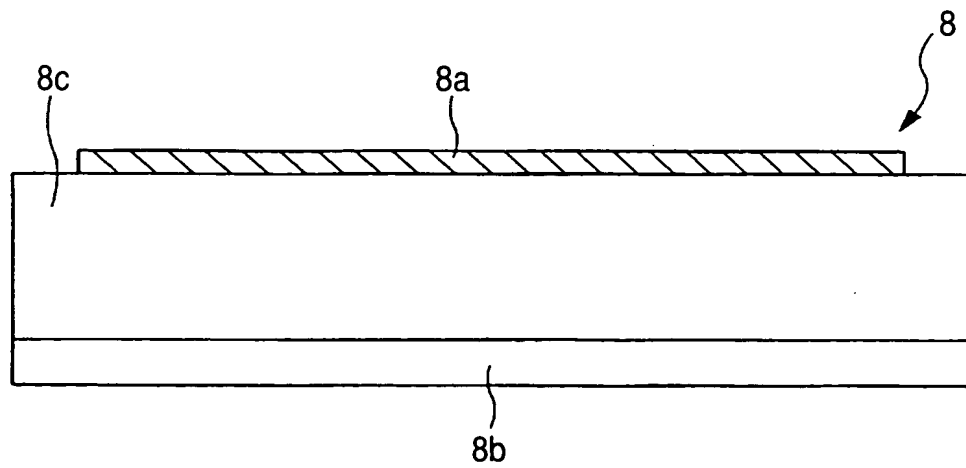


FIG. 7

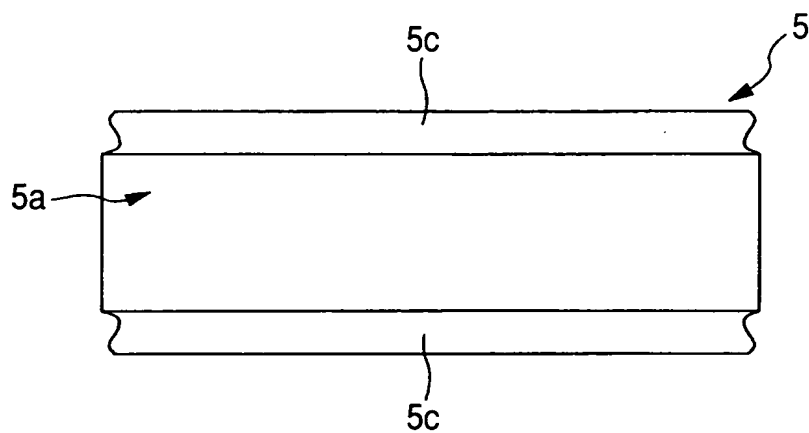


FIG. 8

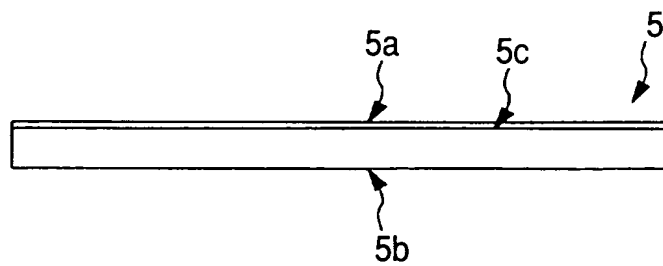


FIG. 9

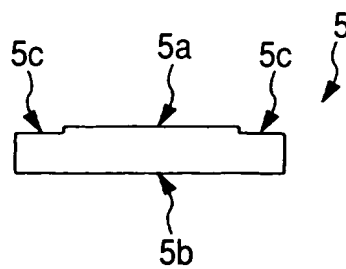


FIG. 10

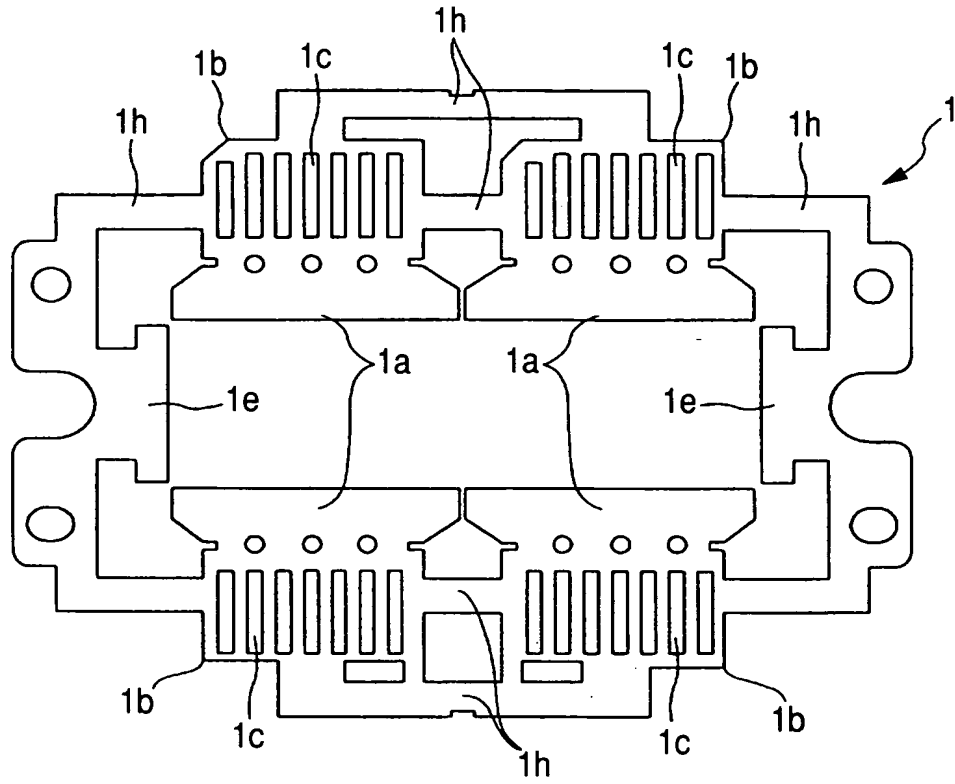


FIG. 11



FIG. 12

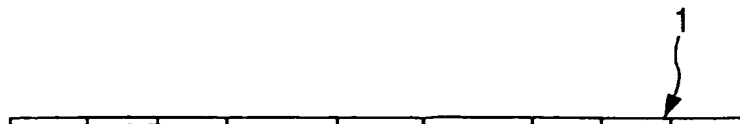


FIG. 13

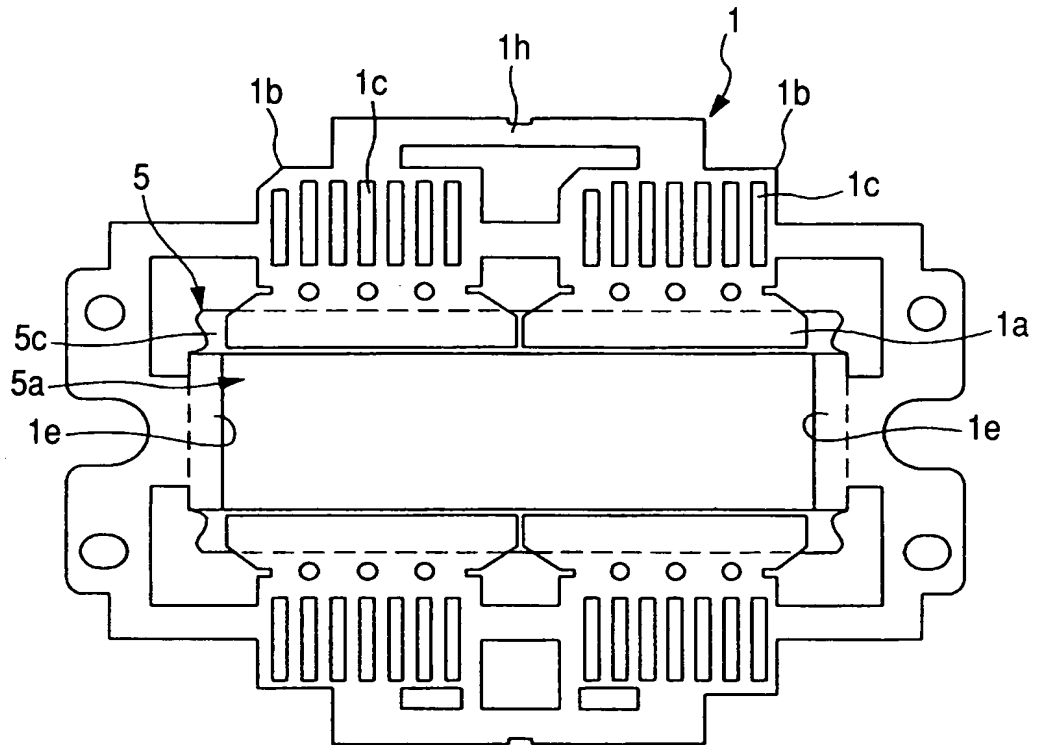


FIG. 14

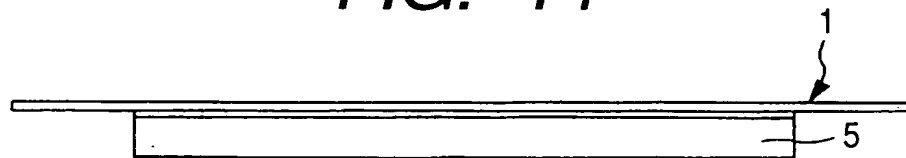
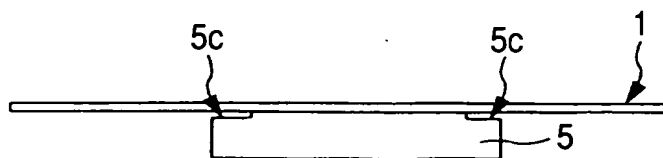


FIG. 15



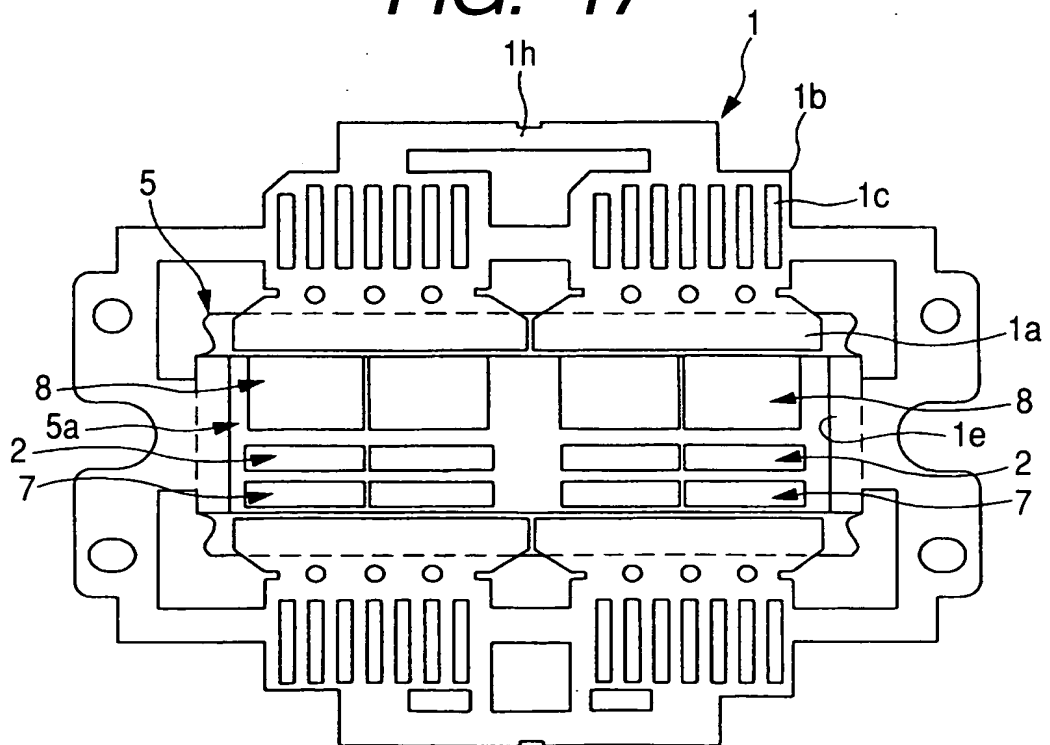


FIG. 18

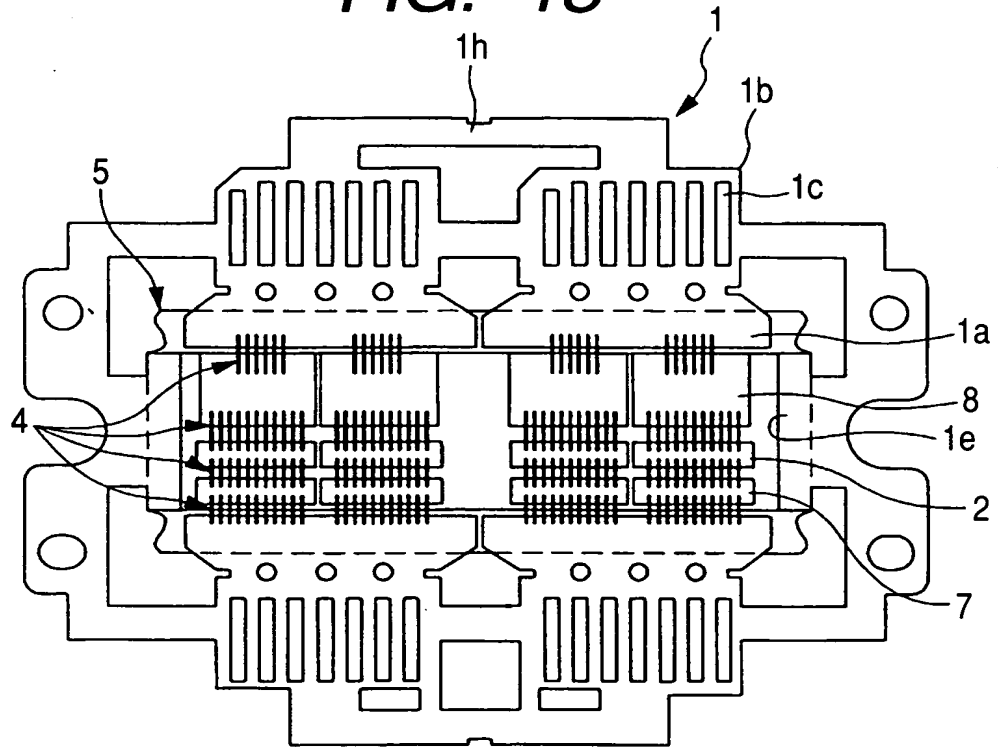


FIG. 19

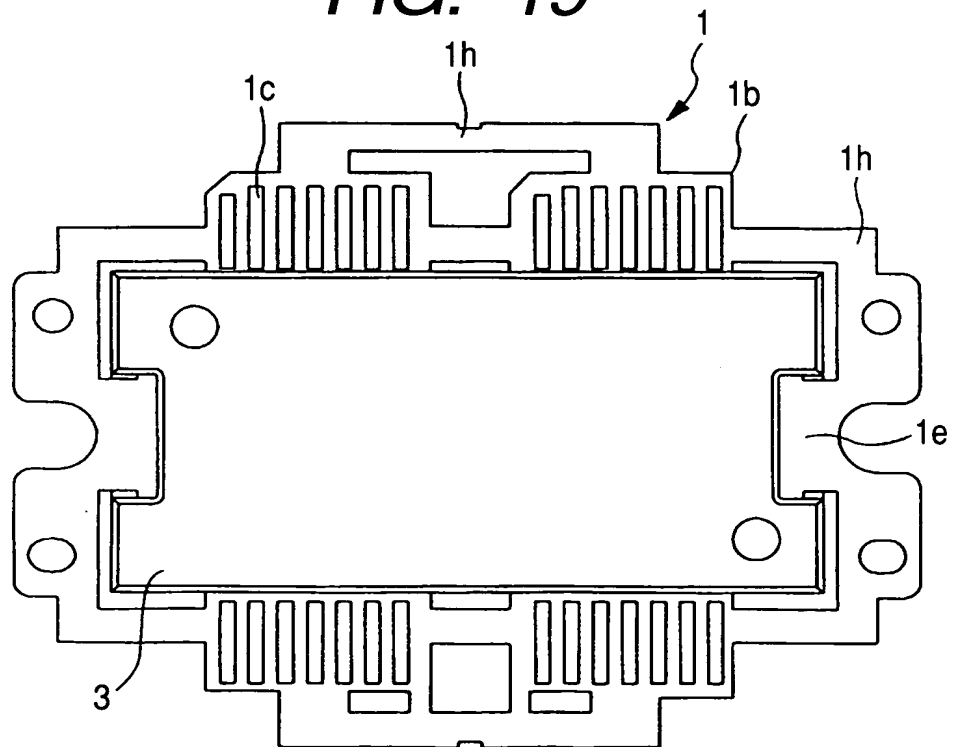


FIG. 20

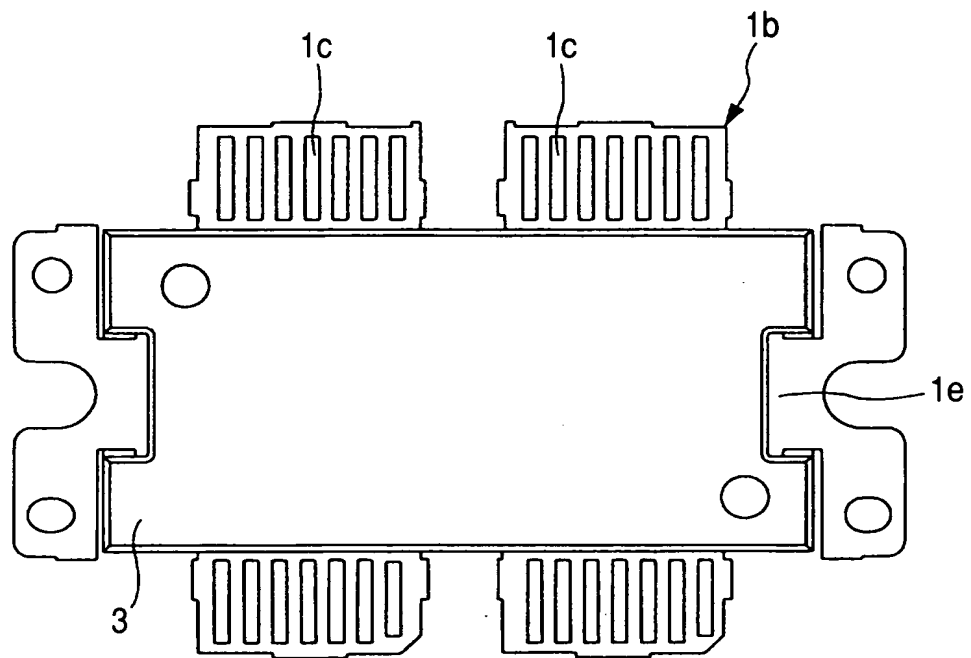


FIG. 21

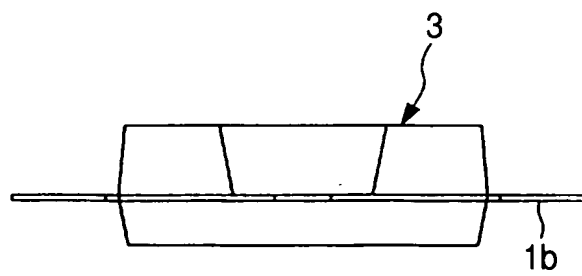


FIG. 22

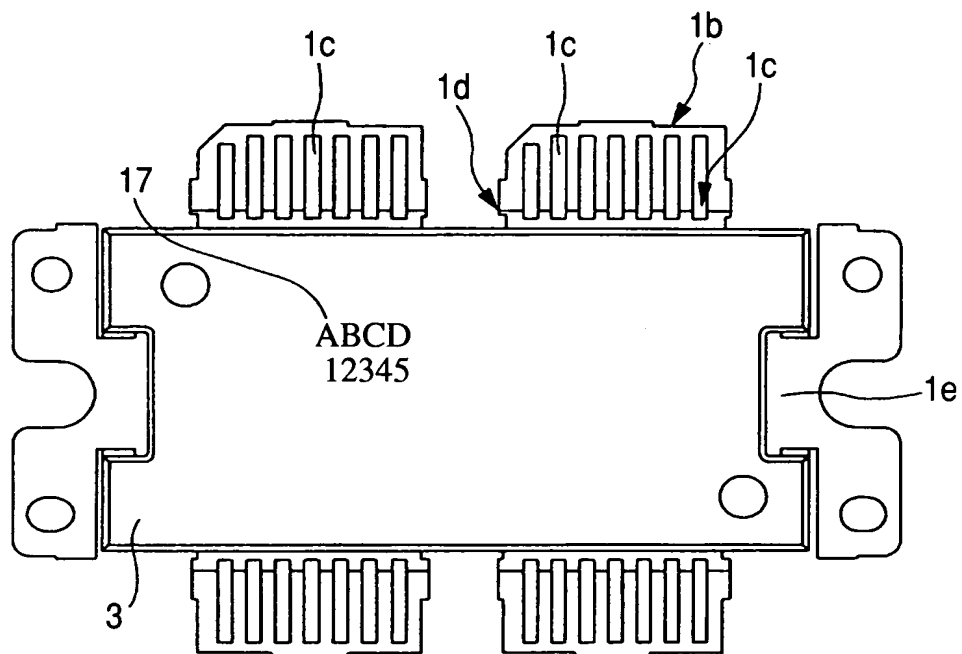


FIG. 23

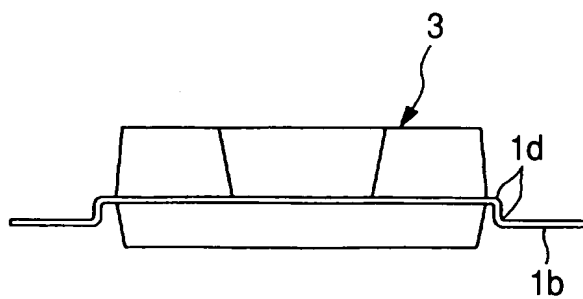


FIG. 24

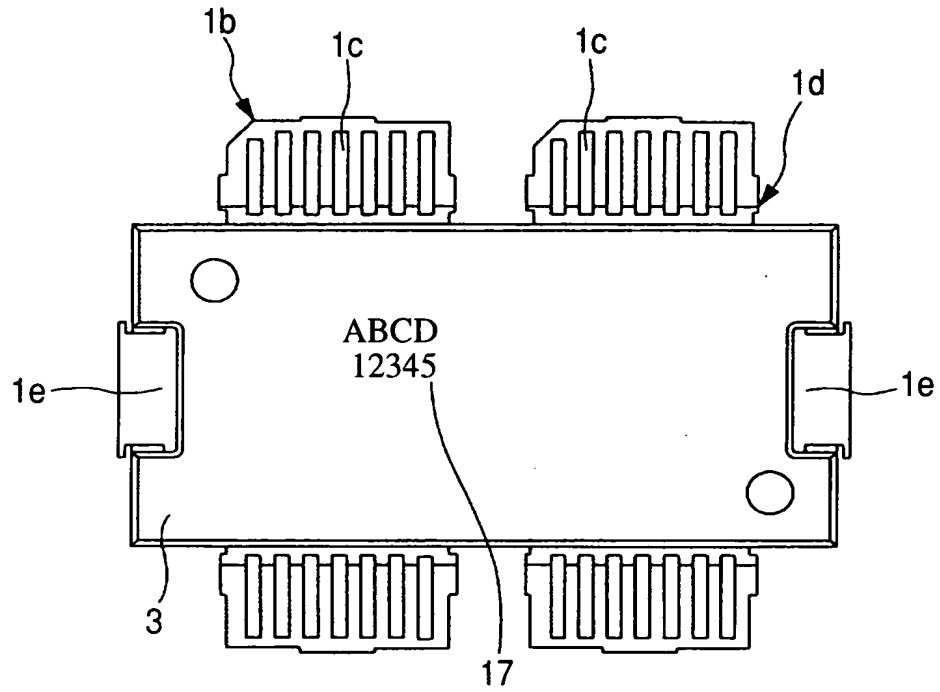


FIG. 25

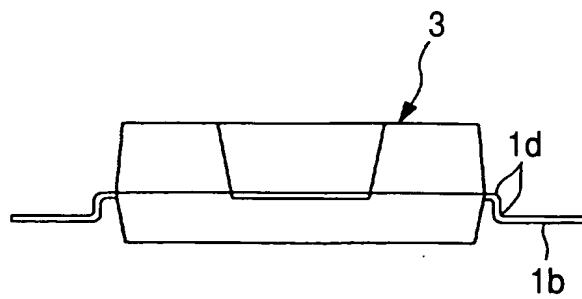


FIG. 26

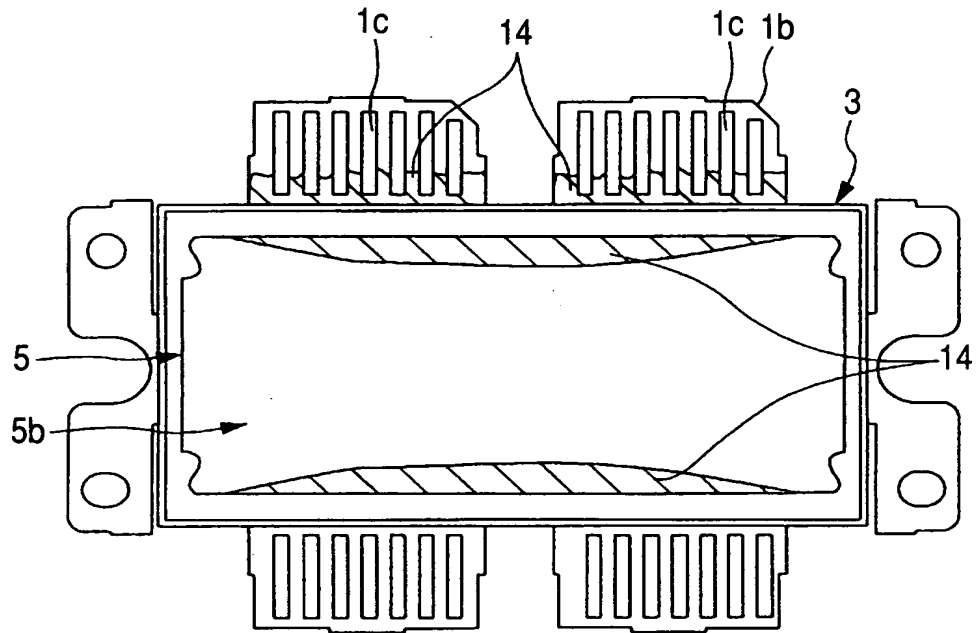


FIG. 27

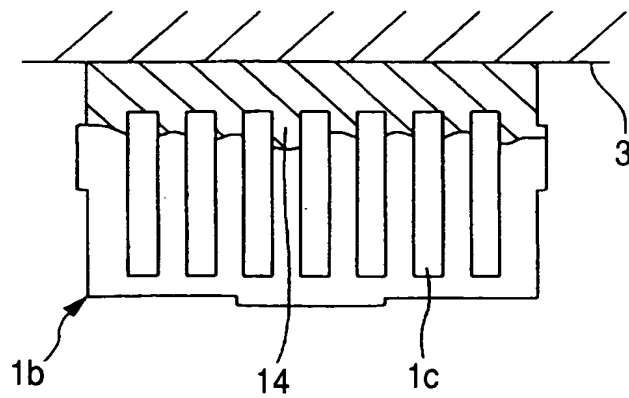
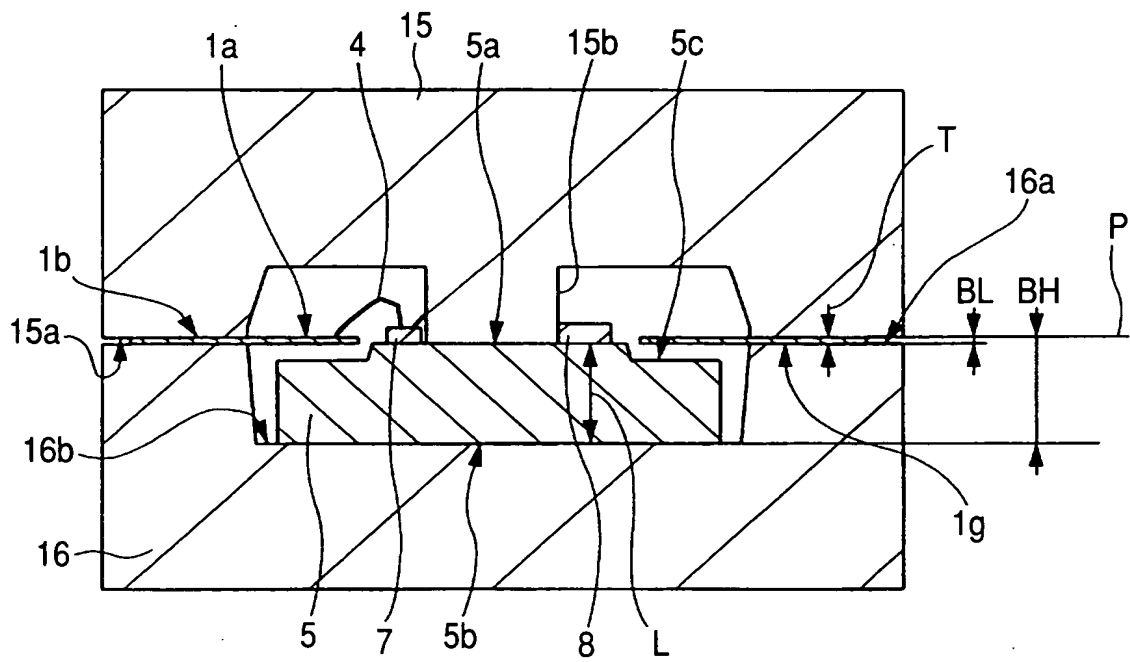


FIG. 28



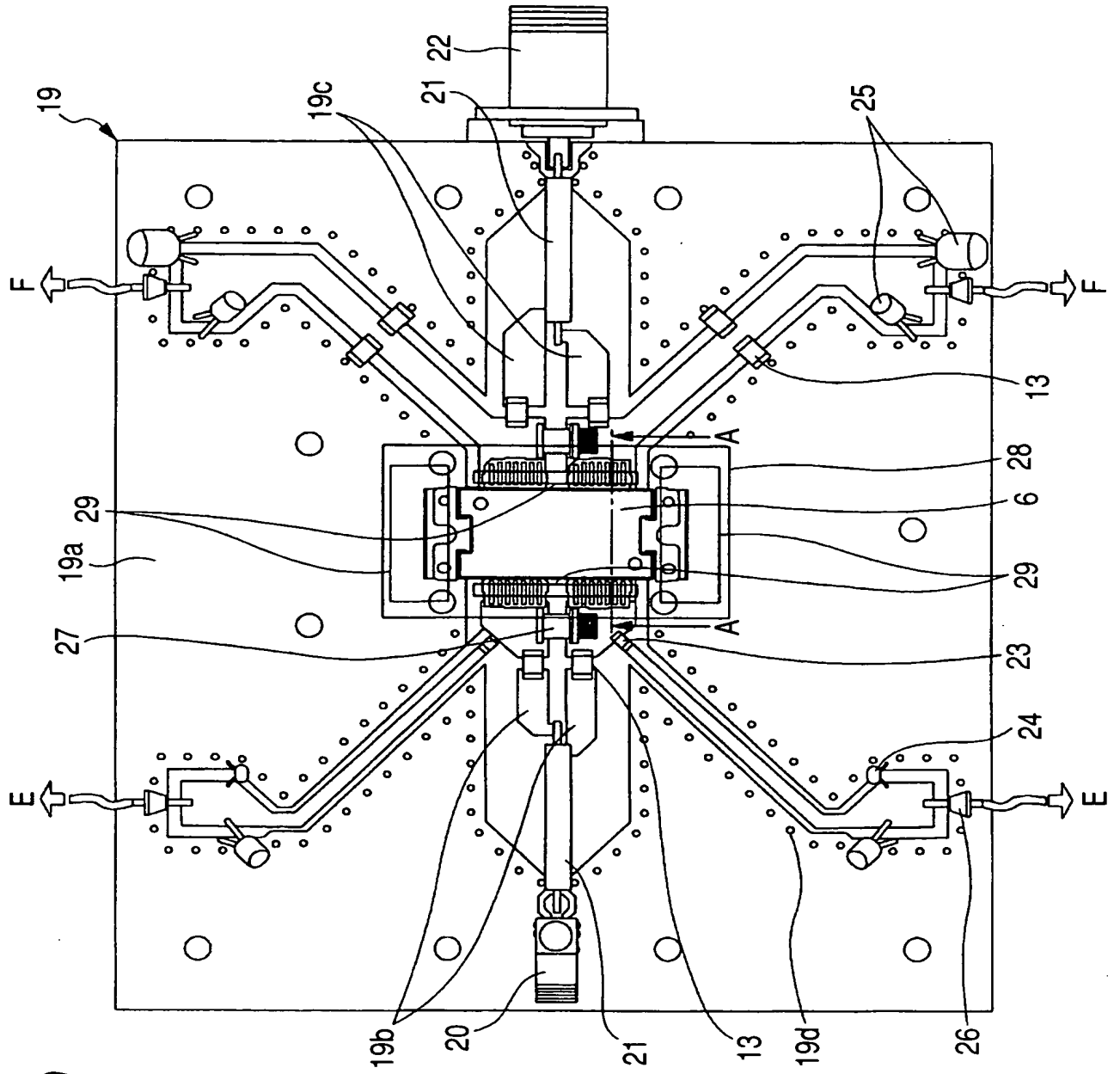


FIG. 29

FIG. 30

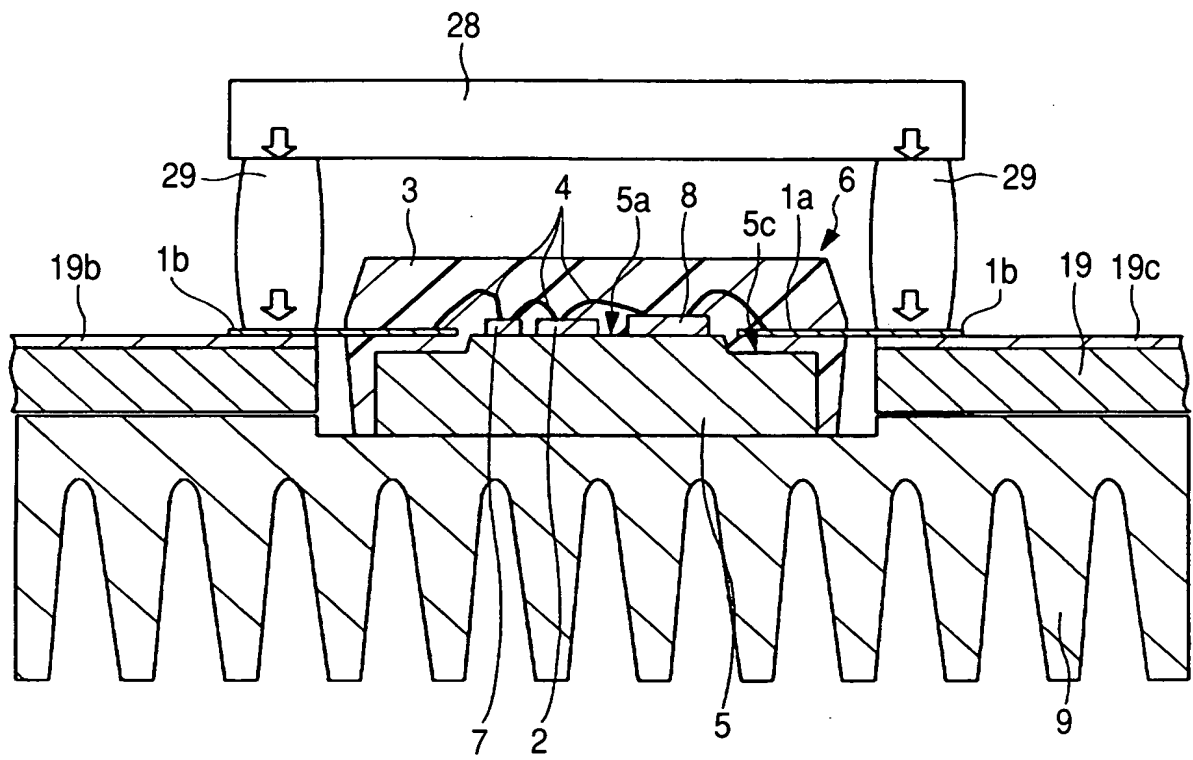


FIG. 31

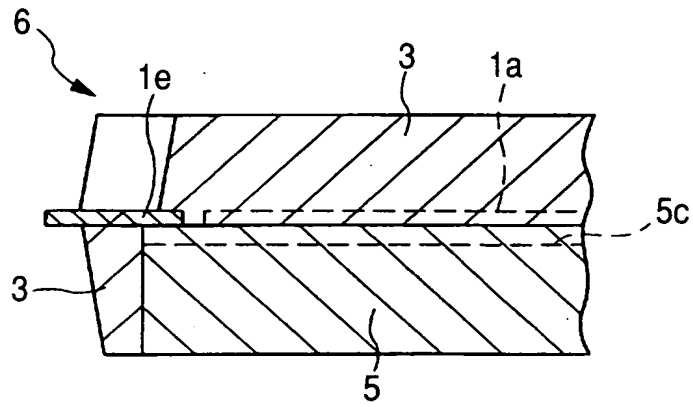


FIG. 32

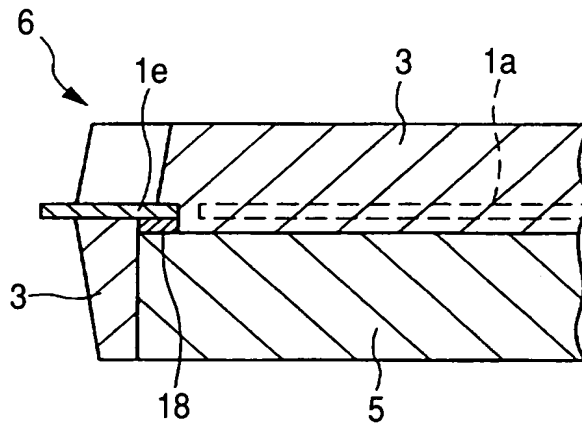


FIG. 33

